TEXAS INSTRUMENTS

SN54LV74A, SN74LV74A

SCLS381M – AUGUST 1997 – REVISED MARCH 2015

SNx4LV74A Dual Positive-Edge-Triggered D-Type Flip-Flops

1 Features

- 2-V to 5.5-V V_{CC} Operation
- Maximum t_{pd} of 8.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 500-V Charged-Device Model (C101)

2 Applications

- Programmable Logic Controller (PLC)
- DCS and PAC: Analog Input Module
- AV Receiver
- Server PSU
- STB, DVR, and Streaming Media (Withdraw)
- Server Motherboard

3 Description

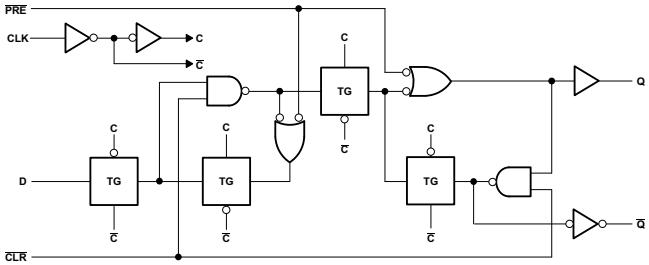
These dual positive-edge-triggered D-type flip-flops are designed for 2-V to 5.5-V V_{CC} operation.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LV74A	VQFN (14)	3.50 mm × 3.50 mm
	SOIC (14)	8.65 mm × 3.91 mm
	SOP (14)	10.30 mm × 5.30 mm
	SSOP (14)	6.20 mm × 5.30 mm
	TSSOP (14)	5.00 mm × 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Logic Diagram, Each Flip-Flop (Positive Logic)



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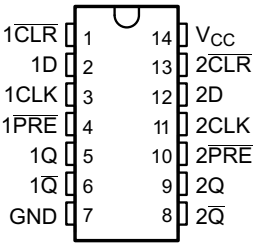
4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

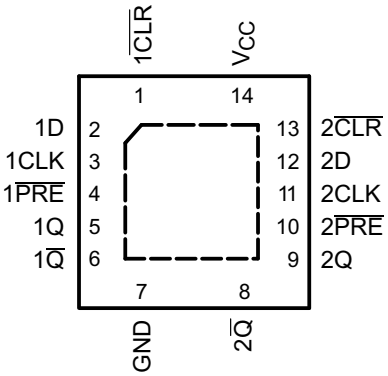
Changes from Revision L (April 2005) to Revision M	Page
• Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1
• Removed Ordering Information table.	1

5 Pin Configuration and Functions

D, DGV, NS, or PW Package
14-PIN SOIC, SOP, SSOP, or TSSOP
Top View



RGY Package
14-PIN VQFN
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	1$\overline{CLR}$	I	1 clear
2	1D	I	1D input
3	1CLK	I	1 clock
4	1$\overline{PRE}$	I	1 preset
5	1Q	O	1Q output
6	1$\overline{Q}$	O	1$\overline{Q}$ output
7	GND	–	GND
8	2$\overline{Q}$	O	2$\overline{Q}$ output
9	2Q	O	2Q output
10	2$\overline{PRE}$	I	2 preset
11	2CLK	I	2 clock
12	2D	I	2D input
13	2$\overline{CLR}$	I	2 clear
14	Vcc	–	Supply voltage input

6 Specifications

6.1 Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	7	V
V_I	Input voltage(2)		–0.5	7	V
V_O	Voltage applied to any output in the high-impedance or power-off state(2)		–0.5	7	V
V_O	Output voltage(2)(3)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
θ_{JA}	Package thermal impedance	D package(4)		86	°C/W
		DB package(4)		96	
		DGV package(4)		127	
		NS package(4)		76	
		PW package(4)		113	
		RGY package(5)		47	
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This value is limited to 5.5 V maximum.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.
(5) The package thermal impedance is calculated in accordance with JESD 51-5.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			SN54LV74A(2)		SN74LV74A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5				V
		V_{CC} = 2.3 V to 2.7 V	V_{CC} × 0.7		V_{CC} × 0.7		
		V_{CC} = 3 V to 3.6 V	V_{CC} × 0.7		V_{CC} × 0.7		
		V_{CC} = 4.5 V to 5.5 V	V_{CC} × 0.7		V_{CC} × 0.7		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		V_{CC} × 0.3		V_{CC} × 0.3	
		V_{CC} = 3 V to 3.6 V		V_{CC} × 0.3		V_{CC} × 0.3	
		V_{CC} = 4.5 V to 5.5 V		V_{CC} × 0.3		V_{CC} × 0.3	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		–50		–50	µA
		V_{CC} = 2.3 V to 2.7 V		–2		–2	mA
		V_{CC} = 3 V to 3.6 V		–6		–6	
		V_{CC} = 4.5 V to 5.5 V		–12		–12	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	µA
		V_{CC} = 2.3 V to 2.7 V		2		2	mA
		V_{CC} = 3 V to 3.6 V		6		6	
		V_{CC} = 4.5 V to 5.5 V		12		12	
Δt/Δv	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V		200		200	ns/V
		V_{CC} = 3 V to 3.6 V		100		100	
		V_{CC} = 4.5 V to 5.5 V		20		20	
T_A	Operating free-air temperature		–55	125	–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, SCBA004.
(2) Product Preview

6.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LV74A(1)			SN74LV74A –40°C to 85°C			SN74LV74A –40°C to 125°C			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}	I_{OH} = –50 µA	2 V to 5.5 V	V_{CC}–0.1			V_{CC}–0.1			V_{CC}–0.1			V
	I_{OH} = –2 mA	2.3 V	2			2			2			
	I_{OH} = –6 mA	3 V	2.48			2.48			2.48			
	I_{OH} = –12 mA	4.5 V	3.8			3.8			3.8			
V_{OL}	I_{OL} = 50 µA	2 V to 5.5 V			0.1			0.1			0.1	V
	I_{OL} = 2 mA	2.3 V			0.4			0.4			0.4	
	I_{OL} = 6 mA	3 V			0.44			0.44			0.44	
	I_{OL} = 12 mA	4.5 V			0.55			0.55			0.55	
I_I	V_I = 5.5 V or GND	0 to 5.5 V			±1			±1			±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			20			20			20	µA
I_{off}	V_I or V_O = 5.5 V	0			5			5			5	µA
C_i	V_I = V_{CC} or GND	3.3 V		2			2			2		pF
		5 V		2			2			2		

(1) Product Preview

6.5 Switching Characteristics: V_{CC} = 2.5 V ± 0.2 V

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	50(2)	100(2)		40(2)		40		40		MHz
			C_L = 50 pF	30	70		25		25		25		
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 15 pF		9.8(2)	14.8(2)	1(2)	17(2)	1	17	1	18	ns
	CLK				11.1(2)	16.4(2)	1(2)	19(2)	1	19	1	20	
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 50 pF		13	17.4	1	20	1	20	1	21	ns
	CLK				14.2	20	1	23	1	23	1	24	

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.6 Switching Characteristics: V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	80(2)	140(2)		70(2)		70		70		MHz
			C_L = 50 pF	50	90		45		45		45		
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 15 pF		6.9(2)	12.3(2)	1(2)	14.5(2)	1	14.5	1	15.5	ns
	CLK				7.9(2)	11.9(2)	1(2)	14(2)	1	14	1	15	
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 50 pF		9.2	15.8	1	18	1	18	1	19	ns
	CLK				10.2	15.4	1	17.5	1	17.5	1	18.5	

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.7 Switching Characteristics: V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	130(2)	180(2)		110(2)		110		110		MHz
			C_L = 50 pF	90	140		75		75		75		
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 15 pF		5(2)	7.7(2)	1(2)	9(2)	1	9	1	10	ns
	CLK				5.6(2)	7.3(2)	1(2)	8.5(2)	1	8.5	1	9.5	
t_{pd}	$\overline{PRE}$ or $\overline{CLR}$	Q or $\overline{Q}$	C_L = 50 pF		6.6	9.7	1	11	1	11	1	12	ns
	CLK				7.2	9.3	1	10.5	1	10.5	1	11.5	

(1) Product Preview
(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

6.8 Timing Requirements: V_{CC} = 2.5 V ± 0.2 V

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 3)

			T_A = 25°C		SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	8		9		9		9		ns
		CLK	8		9		9		9		
t_{su}	Setup time before CLK↑	Data	8		9		9		9		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	7		7		7		7		
t_h	Hold time, data after CLK↑		0.5		0.5		0.5		0.5		ns

(1) Product Preview

6.9 Timing Requirements: V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 3)

			T_A = 25°C		SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	6		7		7		7		ns
		CLK	6		7		7		7		
t_{su}	Setup time before CLK↑	Data	6		7		7		7		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	5		5		5		5		
t_h	Hold time, data after CLK↑		0.5		0.5		0.5		0.5		ns

(1) Product Preview

6.10 Timing Requirements: V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 3)

			T_A = 25°C		SN54LV74A(1)		SN74LV74A –40°C to 85°C		SN74LV74A –40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{PRE}$ or $\overline{CLR}$ low	5		5		5		5		ns
		CLK	5		5		5		5		
t_{su}	Setup time before CLK↑	Data	5		5		5		5		ns
		$\overline{PRE}$ or $\overline{CLR}$ inactive	3		3		3		3		
t_h	Hold time, data after CLK↑		0.5		0.5		0.5		0.5		ns

(1) Product Preview

6.11 Noise Characteristics(1)

V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C

PARAMETER		SN74LV74A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.1	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		0	–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

6.12 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF	f = 10 MHz	3.3 V	21	pF
				5 V	23	

6.13 Typical Characteristics

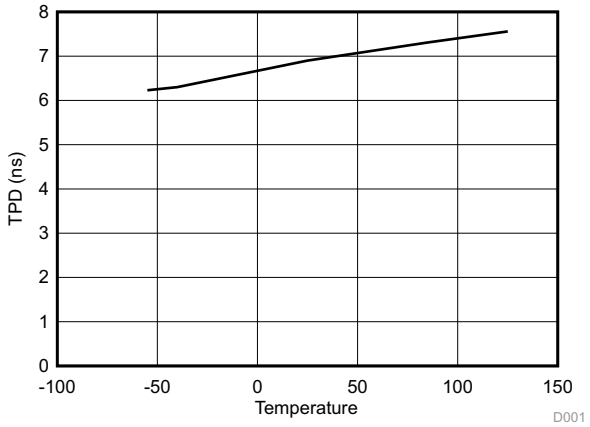


Figure 1. TPD vs. Temperature at 3.3 V

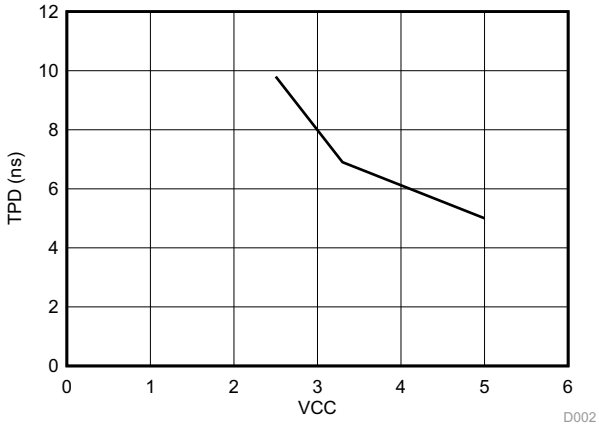
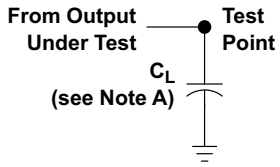
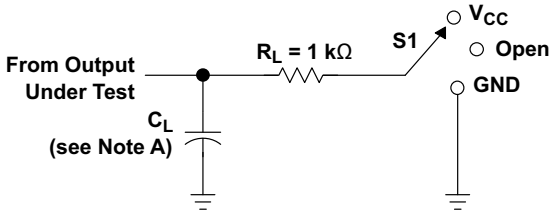


Figure 2. TPD vs. VCC at 25°C

7 Parameter Measurement Information

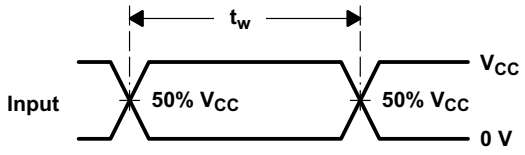


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

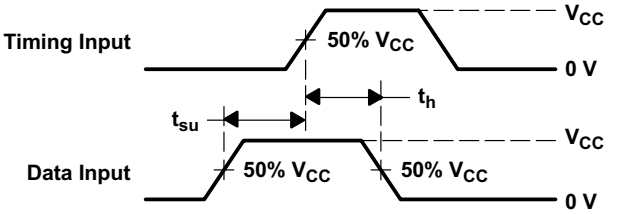


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

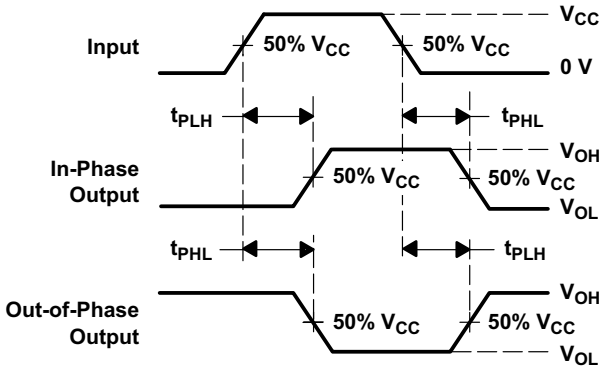
LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS



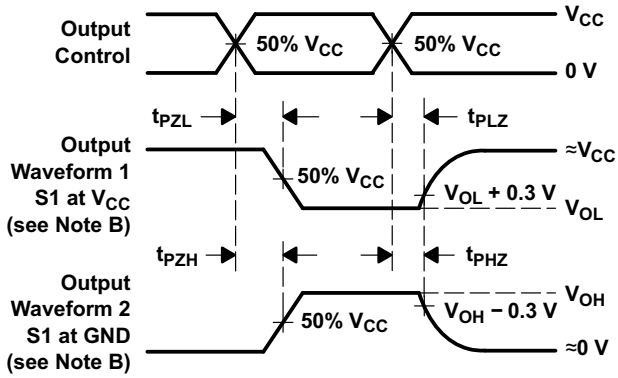
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time, with one input transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PHL} and t_{PLH} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

These dual positive-edge-triggered D-type flip-flops are designed for 2-V to 5.5-V V_{CC} operation.

A low level at the preset ($\overline{PRE}$) or clear ($\overline{CLR}$) inputs sets or resets the outputs, regardless of the levels of the other inputs. When $\overline{PRE}$ and $\overline{CLR}$ are inactive (high), data at the data (D) inputs meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs. The state of the output upon power-up is not known until the first valid clock edge has occurred while V_{CC} is within *Recommended Operating Conditions*.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

8.2 Functional Block Diagram

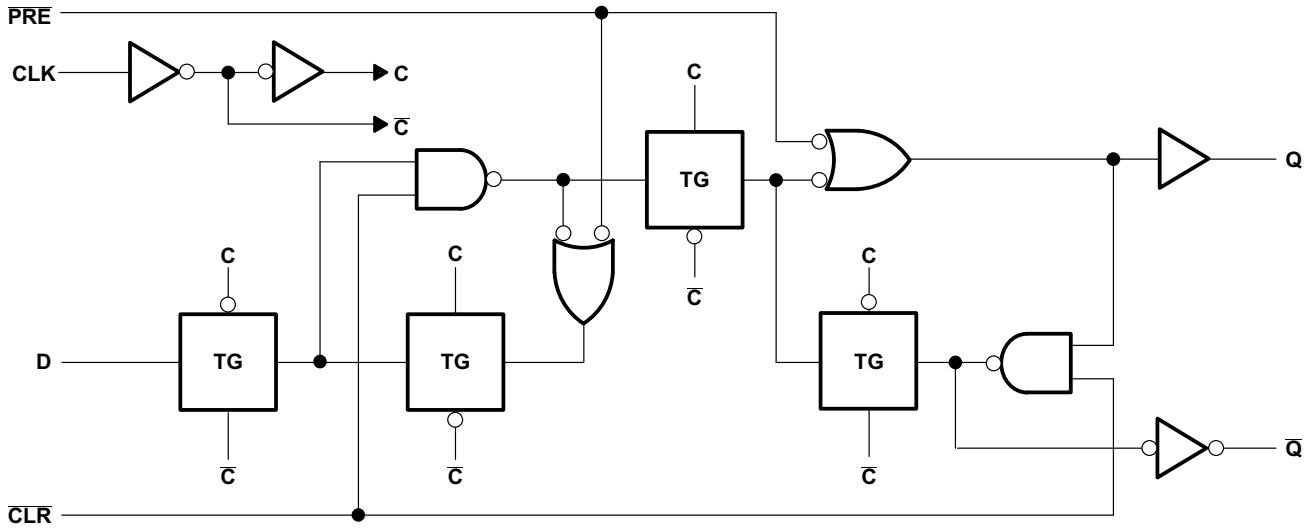


Figure 4. Logic Diagram, Each Flip-Flop (Positive Logic)

8.3 Feature Description

The device's wide operating range allows it to be used in a variety of systems that use different logic levels. The low propagation delay allows fast switching and higher speeds of operation. In addition, the low ground bounce stabilizes the performance of non-switching outputs while another output is switching.

8.4 Device Functional Modes

Table 1. Function Table

INPUTS				OUTPUTS	
$\overline{PRE}$	$\overline{CLR}$	CLK	D	Q	Q
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H(1)	H(1)
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

(1) This configuration is nonstable; that is, it does not persist when $\overline{PRE}$ or $\overline{CLR}$ returns to its inactive (high) level.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74LV74A is a Low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs can accept voltages to 5.5 V at any valid V_{CC} making it Ideal for down translation.

9.2 Typical Application

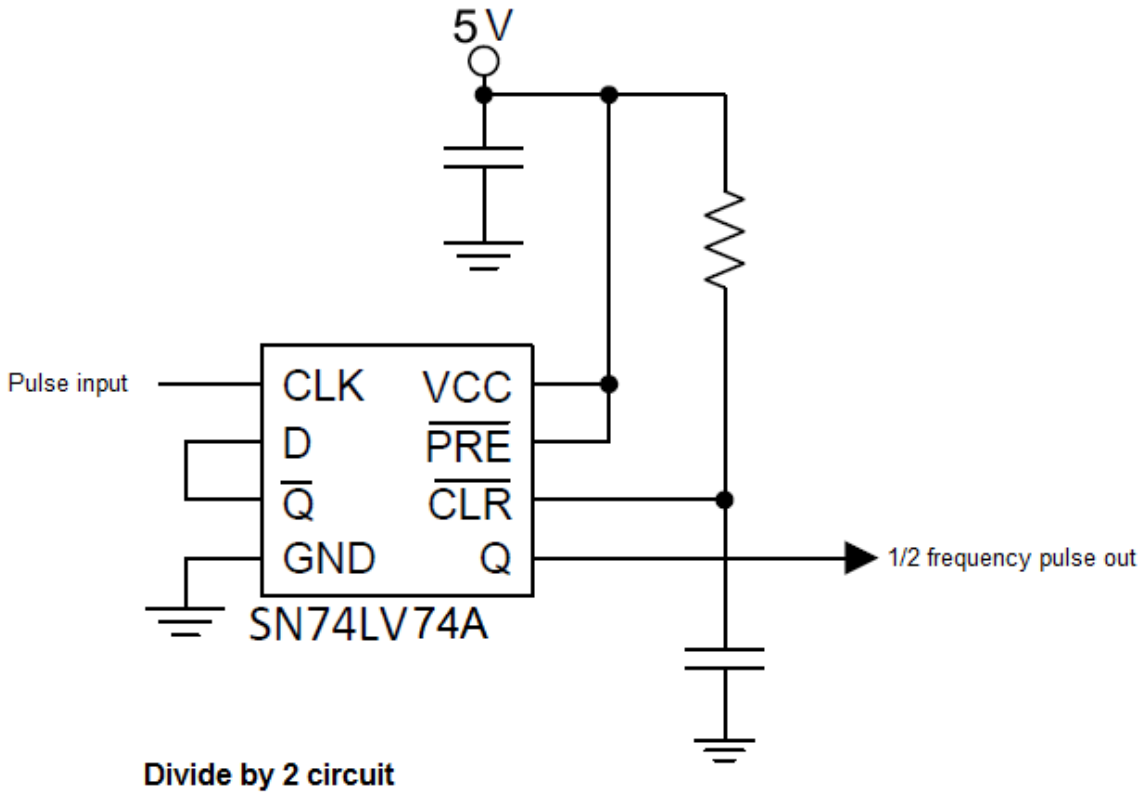


Figure 5. Typical Application Schematic

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so consider routing and load conditions to prevent ringing.

Typical Application (continued)

9.2.2 Detailed Design Procedure

- Recommended input conditions:
  - Specified High and low levels. See (V_{IH} and V_{IL}) in *Recommended Operating Conditions*.
  - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}.
- Recommended output conditions:
  - Load currents should not exceed 25 mA per output and 50 mA total for the part.
  - Outputs should not be pulled above V_{CC}.

9.2.3 Application Curves

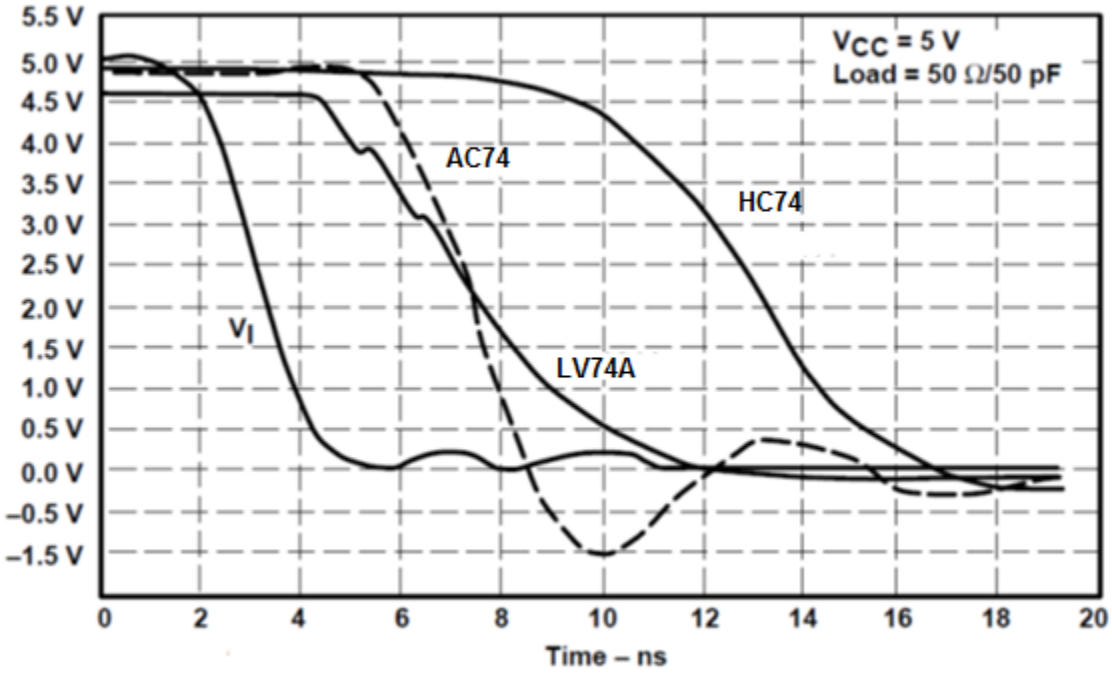


Figure 6. Switching Characteristics Comparison

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1-µF capacitor and if there are multiple V_{CC} terminals then TI recommends a 0.01-µF or 0.022-µF capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1 µF and 1 µF are commonly used in parallel. The bypass capacitor should be installed as close as possible to the power terminal for best results.

11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O's so they also cannot float when disabled.

11.2 Layout Example

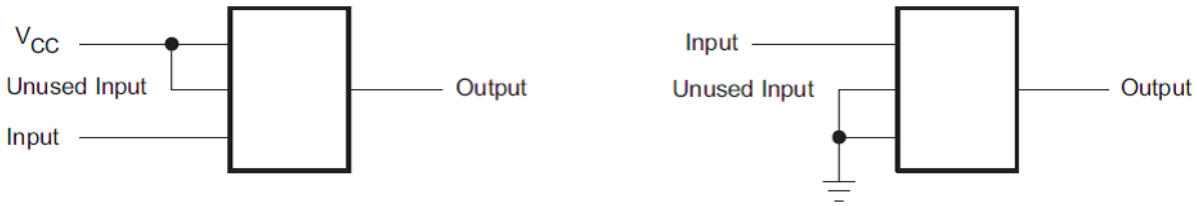


Figure 7. Layout Recommendation

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

Implications of Slow or Floating CMOS Inputs, SCBA004

12.2 Trademarks

All trademarks are the property of their respective owners.

12.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV74AD	Obsolete	Production	SOIC (D) | 14	-	-	Call TI	Call TI	-40 to 125	LV74A
SN74LV74ADBR	Active	Production	SSOP (DB) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ADBR.A	Active	Production	SSOP (DB) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ADGVR	Active	Production	TVSOP (DGV) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ADGVR.A	Active	Production	TVSOP (DGV) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ADR	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU | SN | NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ADR.A	Active	Production	SOIC (D) | 14	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ANSR	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV74A
SN74LV74ANSR.A	Active	Production	SOP (NS) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV74A
SN74LV74APW	Obsolete	Production	TSSOP (PW) | 14	-	-	Call TI	Call TI	-40 to 125	LV74A
SN74LV74APWR	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74APWR.A	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74APWRG4	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74APWRG4.A	Active	Production	TSSOP (PW) | 14	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74APWT	Obsolete	Production	TSSOP (PW) | 14	-	-	Call TI	Call TI	-40 to 125	LV74A
SN74LV74ARGYR	Active	Production	VQFN (RGY) | 14	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ARGYR.A	Active	Production	VQFN (RGY) | 14	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ARGYRG4	Active	Production	VQFN (RGY) | 14	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A
SN74LV74ARGYRG4.A	Active	Production	VQFN (RGY) | 14	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV74A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LV74A :

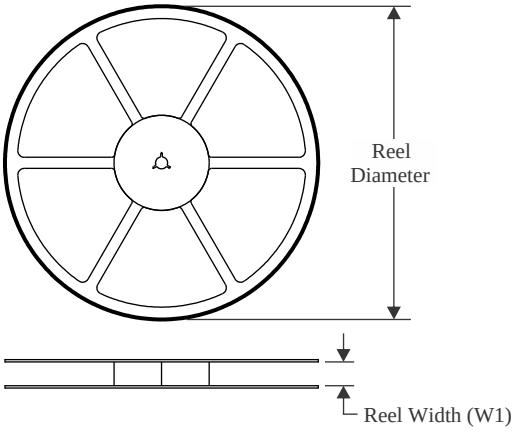
- Automotive : SN74LV74A-Q1
- Enhanced Product : SN74LV74A-EP

NOTE: Qualified Version Definitions:

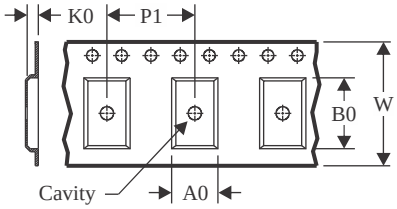
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

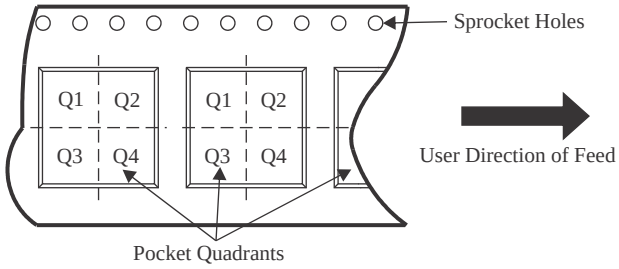


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

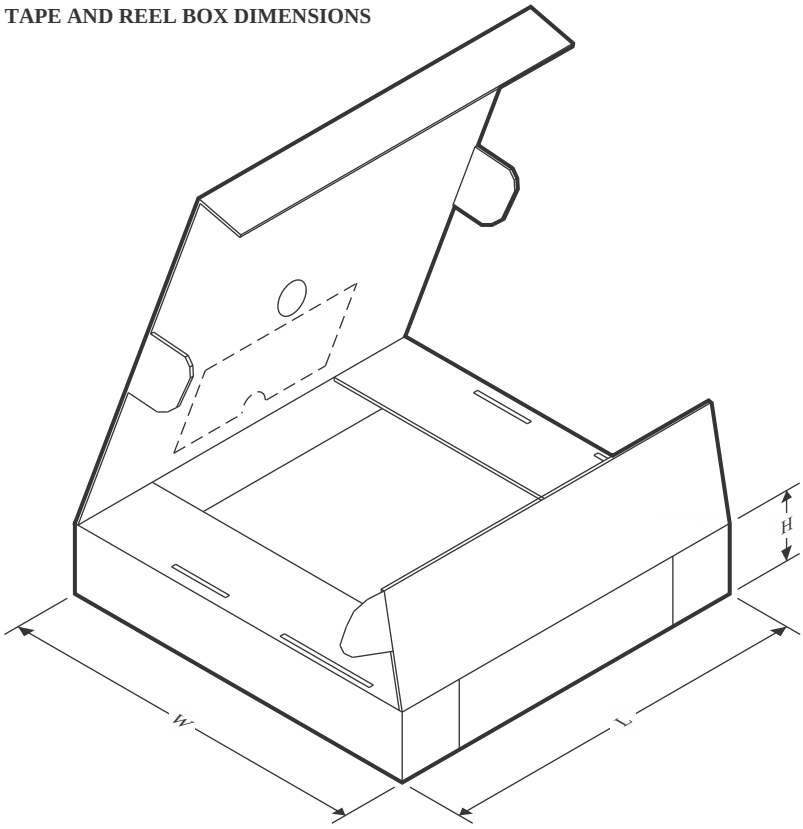
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV74ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV74ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV74ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV74ANSR	SOP	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74LV74APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV74APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV74ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1
SN74LV74ARGYRG4	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV74ADBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74LV74ADGVR	TVSOP	DGV	14	2000	353.0	353.0	32.0
SN74LV74ADR	SOIC	D	14	2500	353.0	353.0	32.0
SN74LV74ANSR	SOP	NS	14	2000	353.0	353.0	32.0
SN74LV74APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV74APWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74LV74ARGYR	VQFN	RGY	14	3000	360.0	360.0	36.0
SN74LV74ARGYRG4	VQFN	RGY	14	3000	360.0	360.0	36.0

GENERIC PACKAGE VIEW

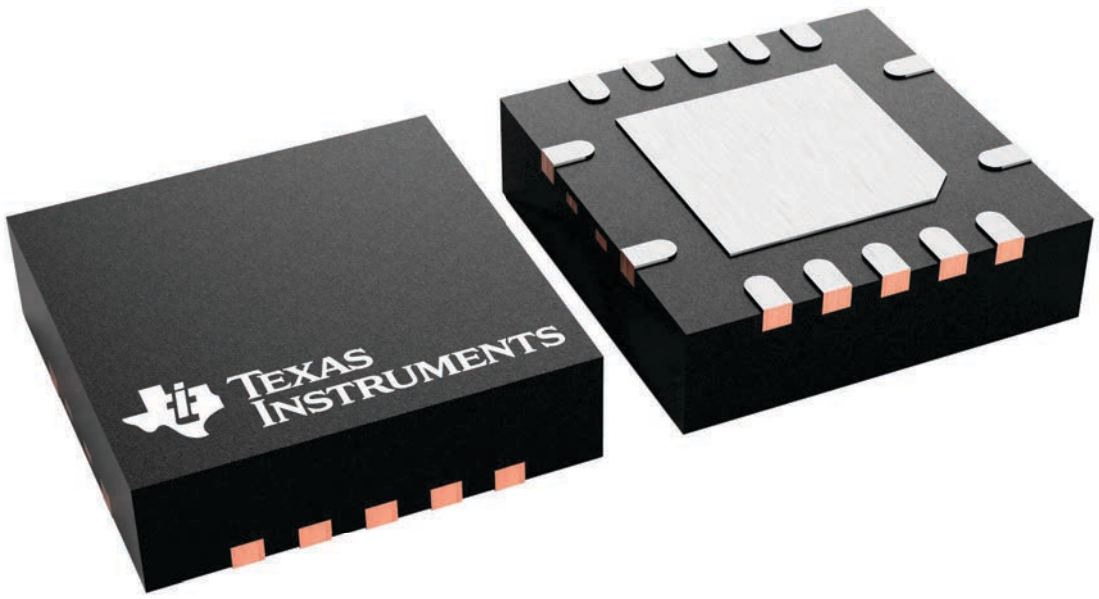
RGY 14

VQFN - 1 mm max height

3.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



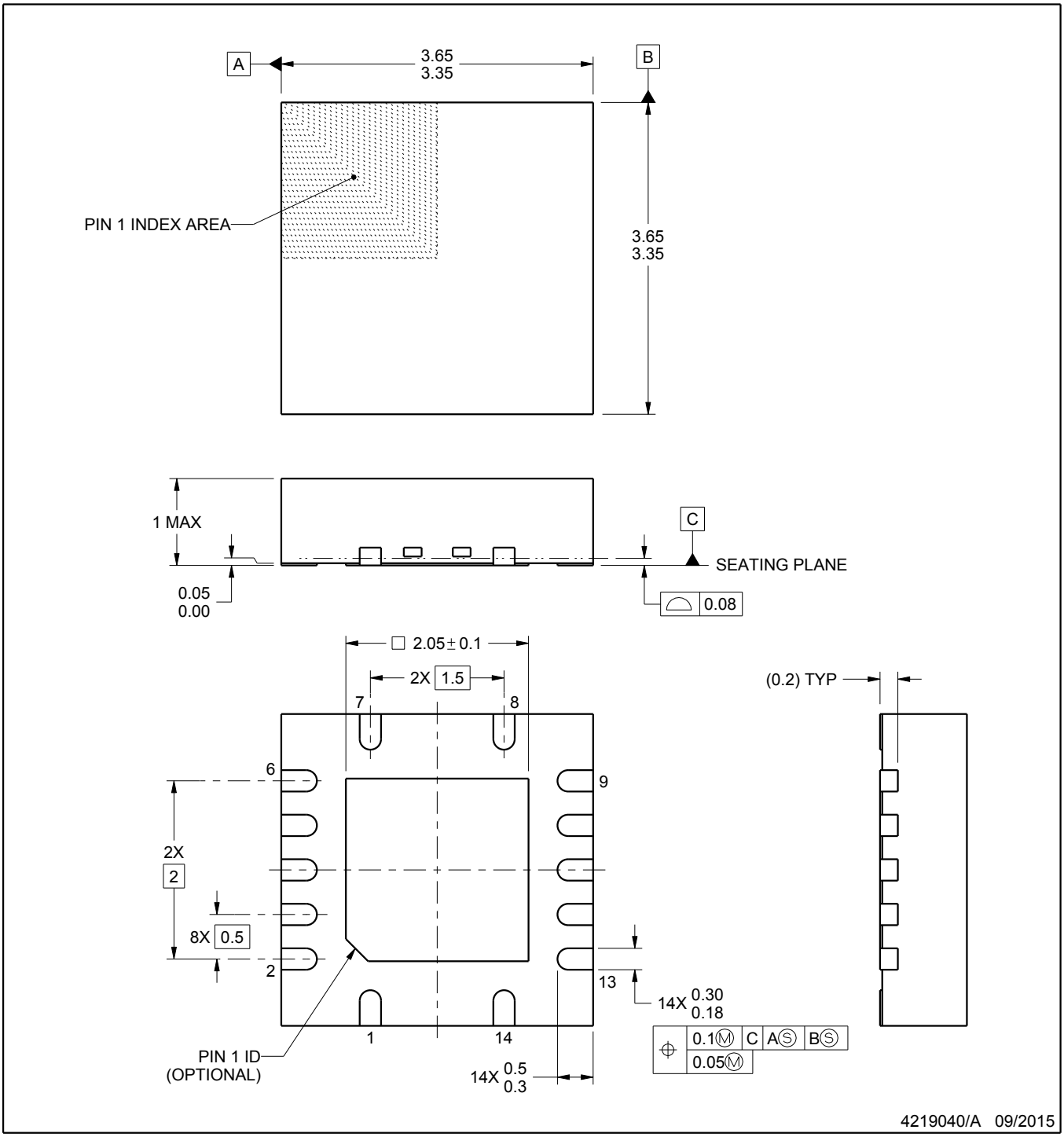
4231541/A

PACKAGE OUTLINE

RGY0014A

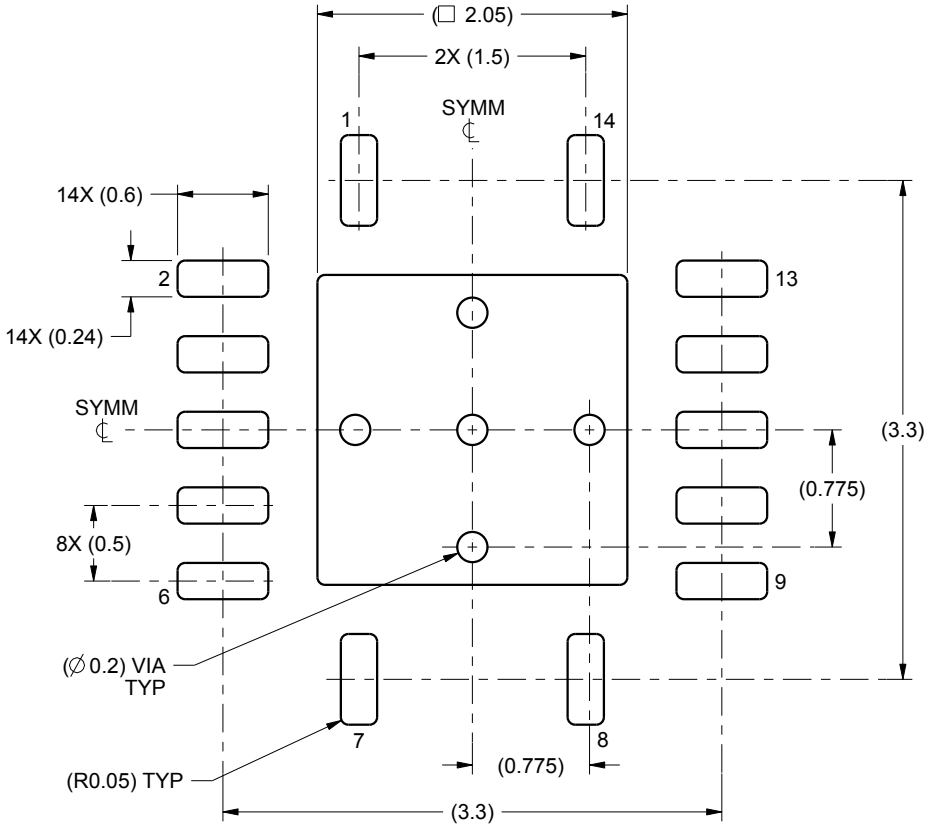
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

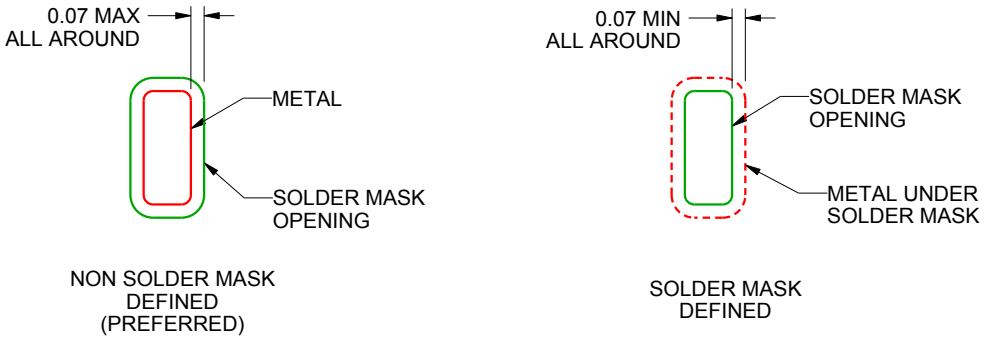


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
SCALE:20X

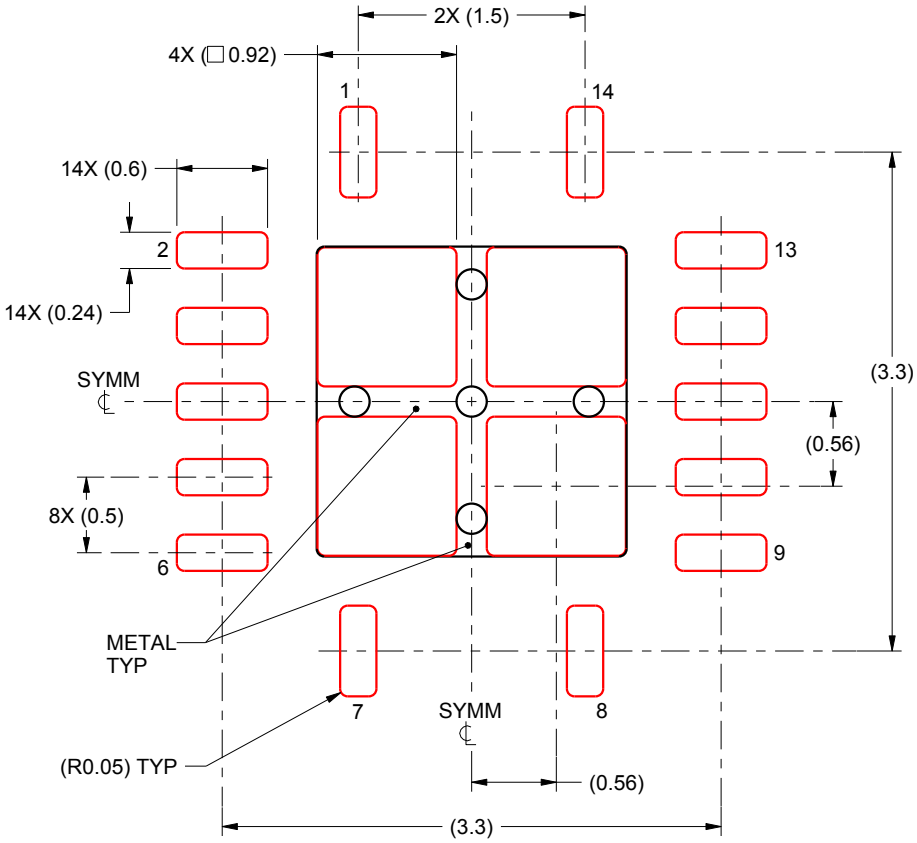


SOLDER MASK DETAILS

4219040/A 09/2015

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
80% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

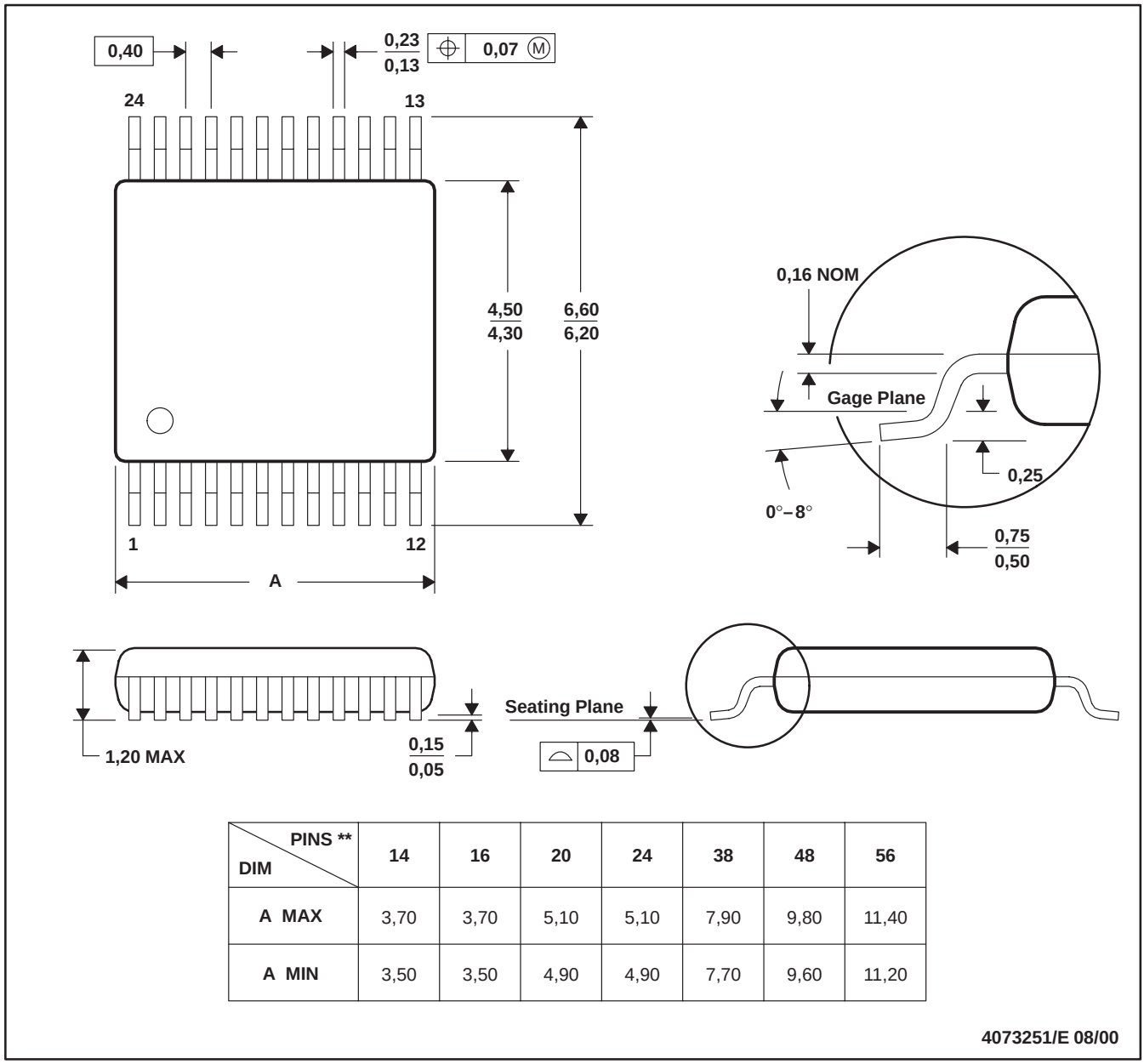
4219040/A 09/2015

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN



DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

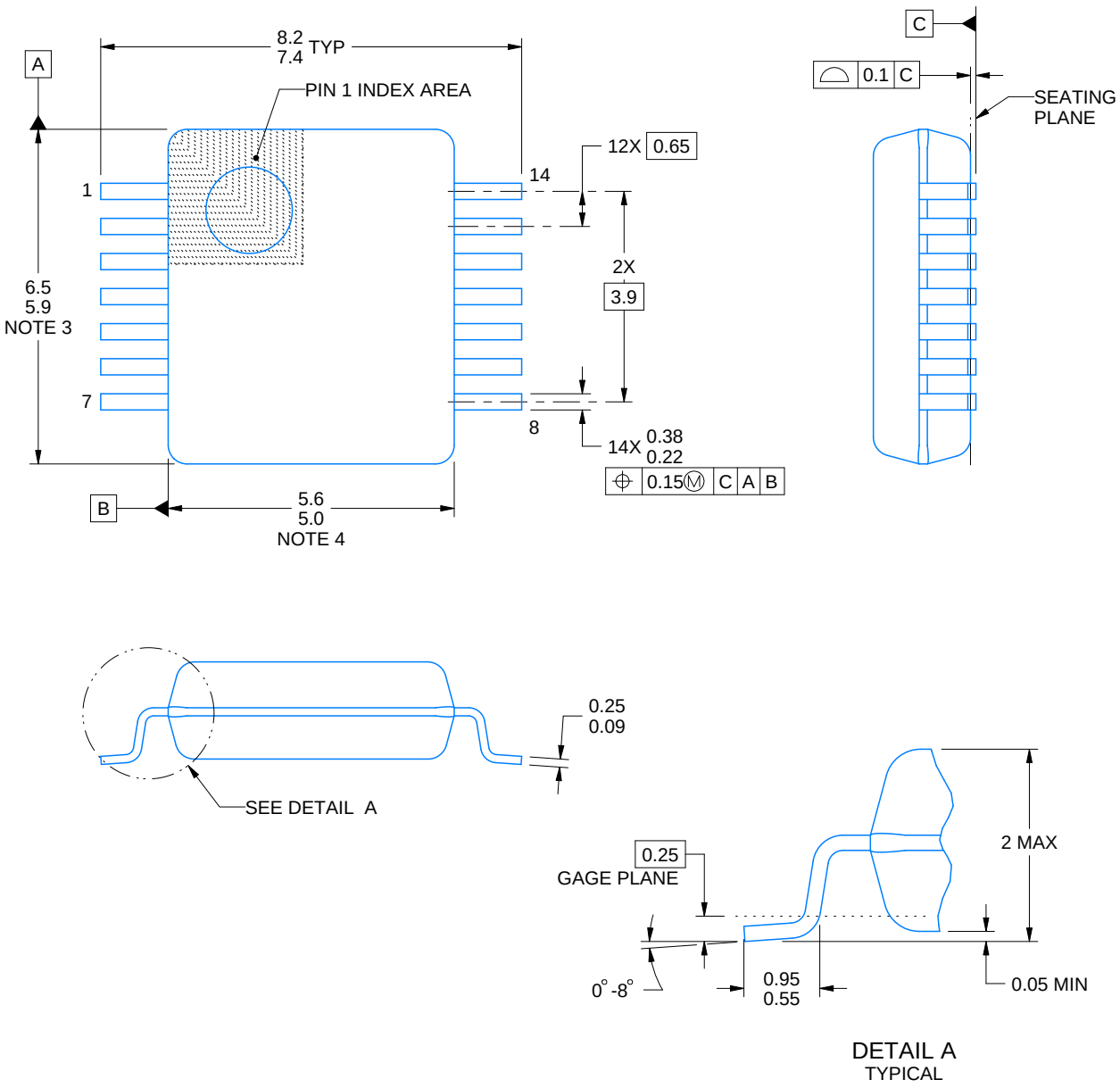
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

PACKAGE OUTLINE

DB0014A

SSOP - 2 mm max height

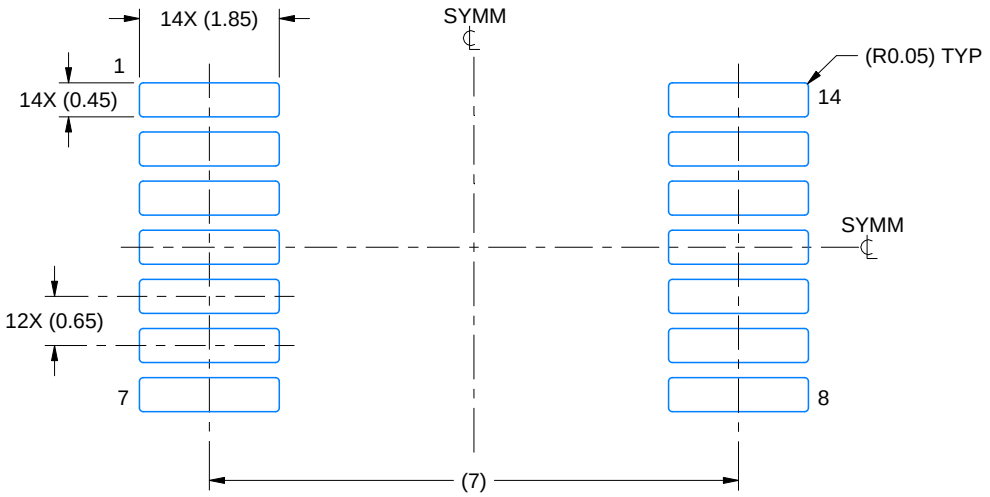
SMALL OUTLINE PACKAGE



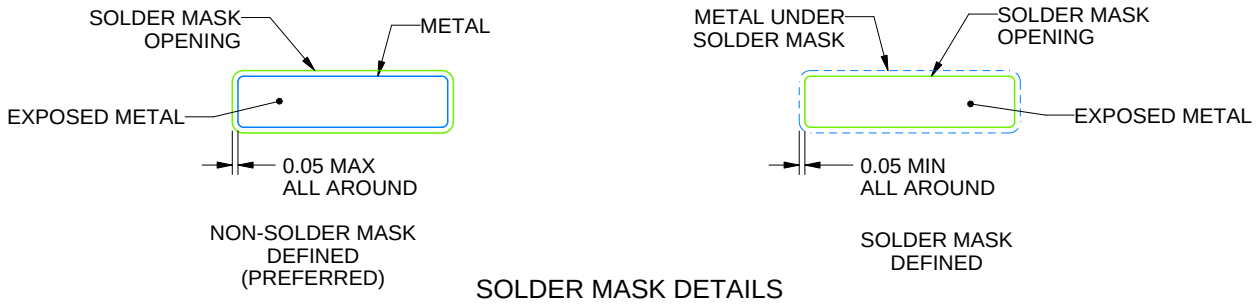
4220762/A 05/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

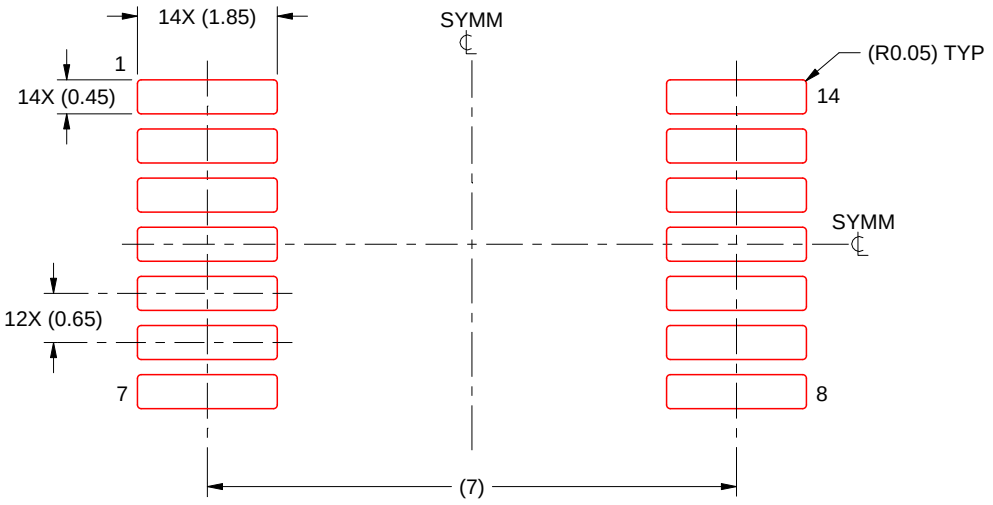


SOLDER MASK DETAILS

4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

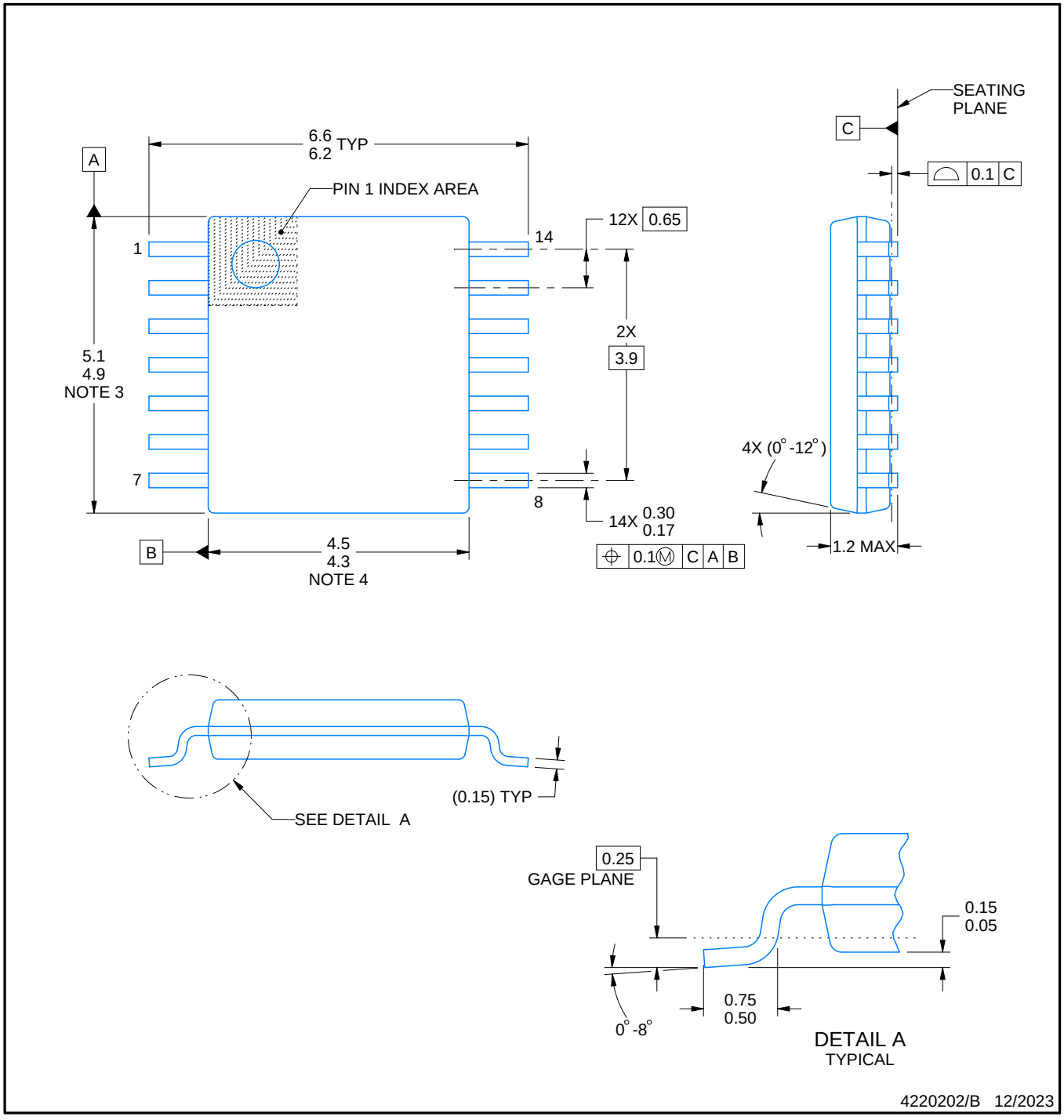
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0014A

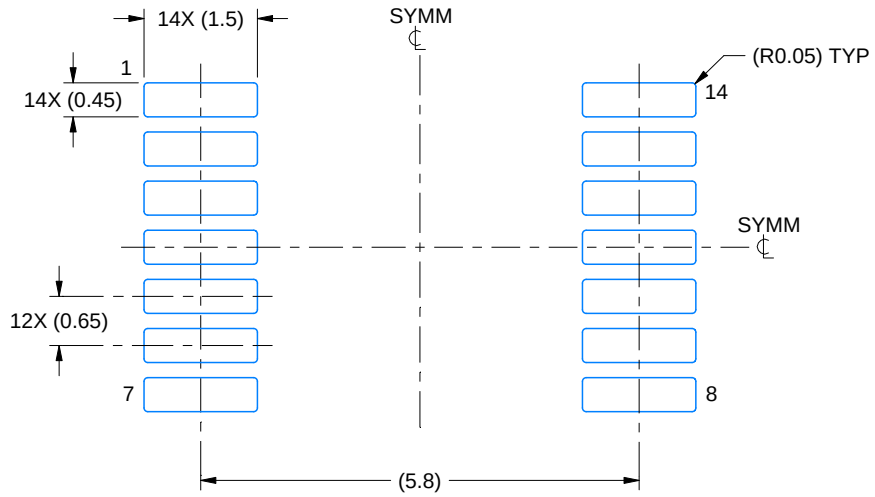
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

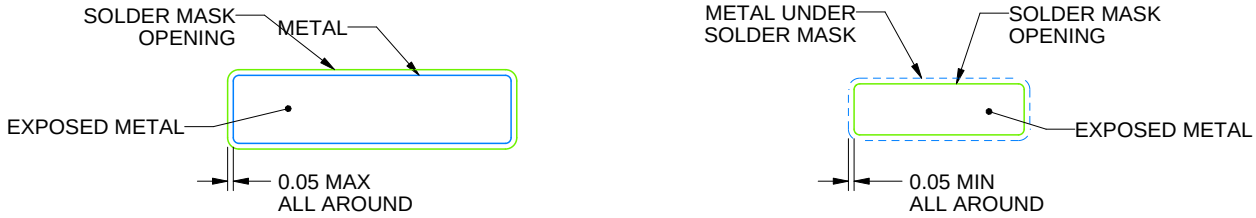


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

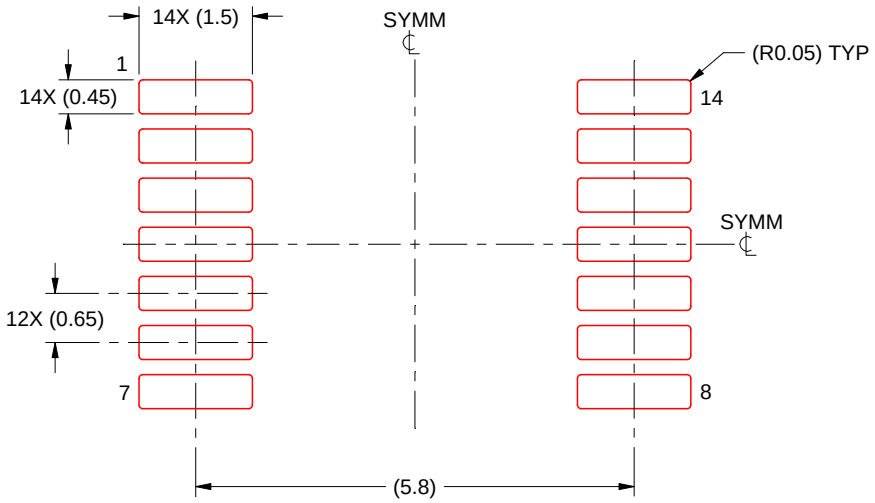


SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

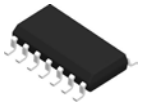


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

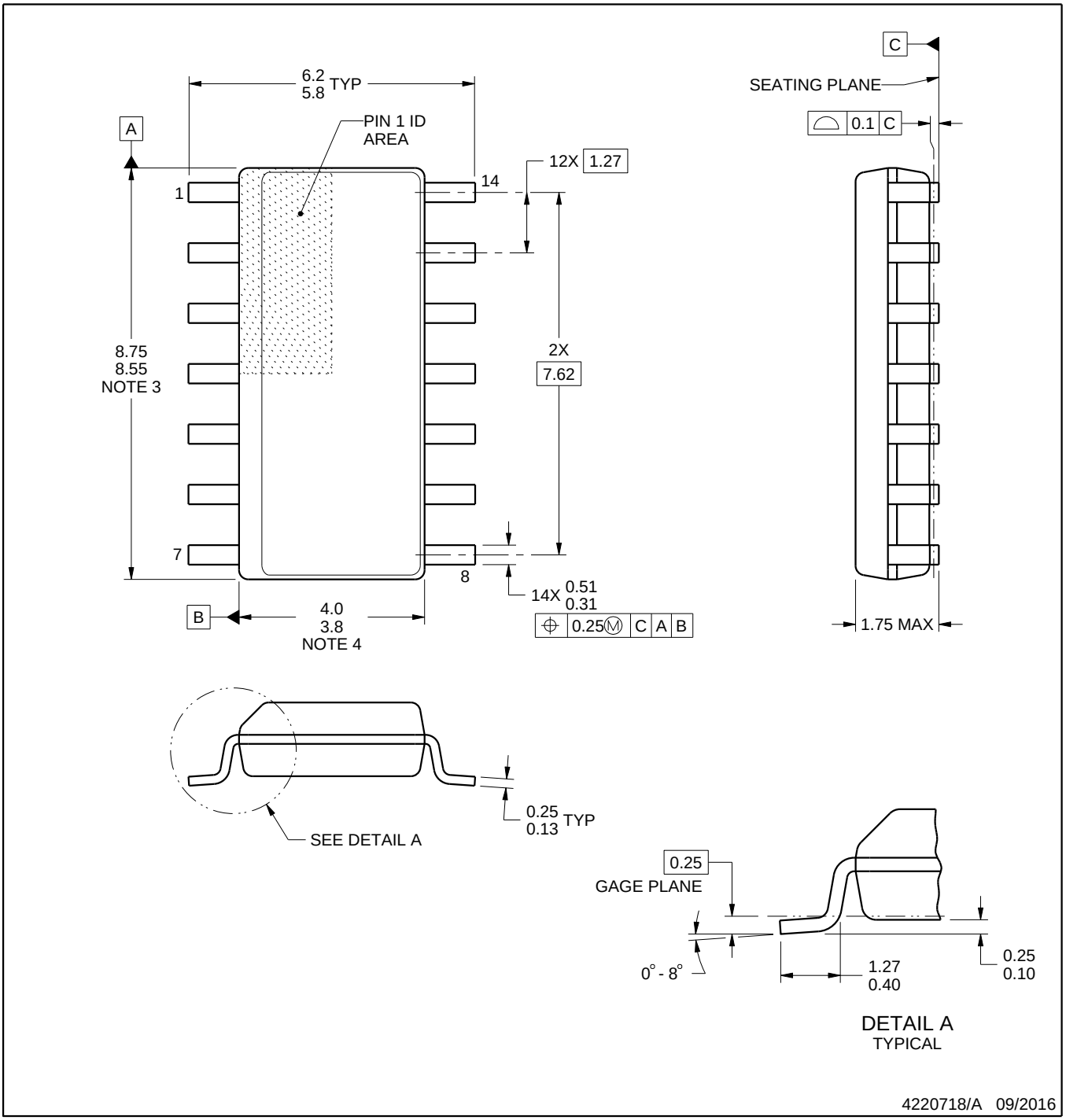


PACKAGE OUTLINE

D0014A

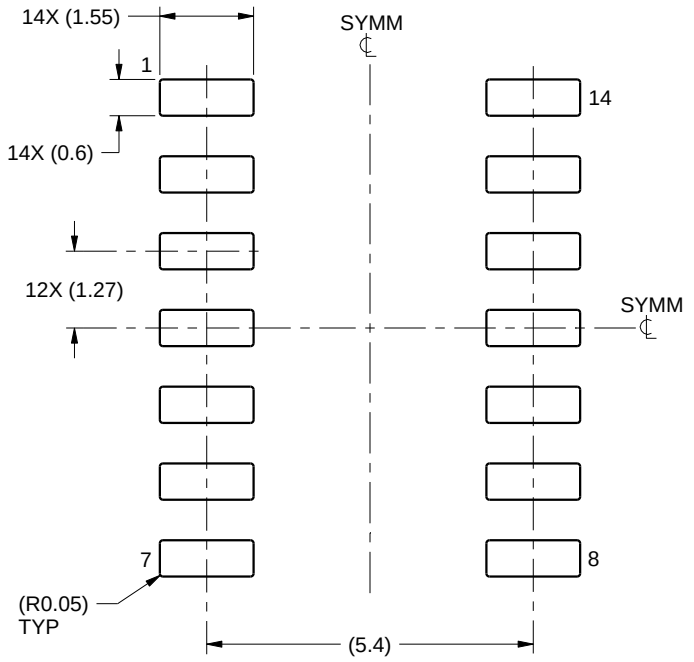
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

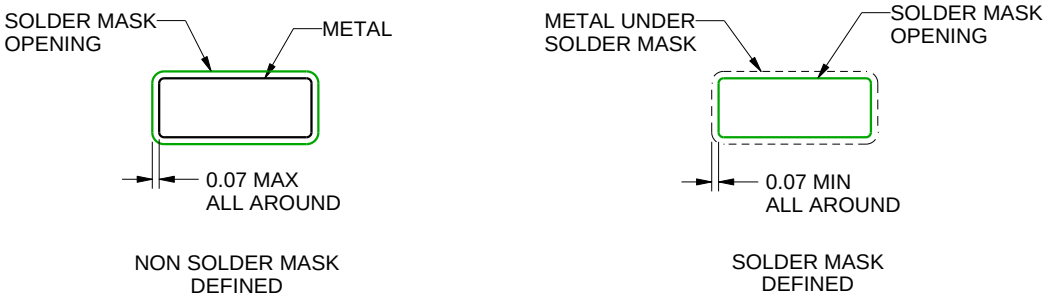


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

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NOTES: (continued)

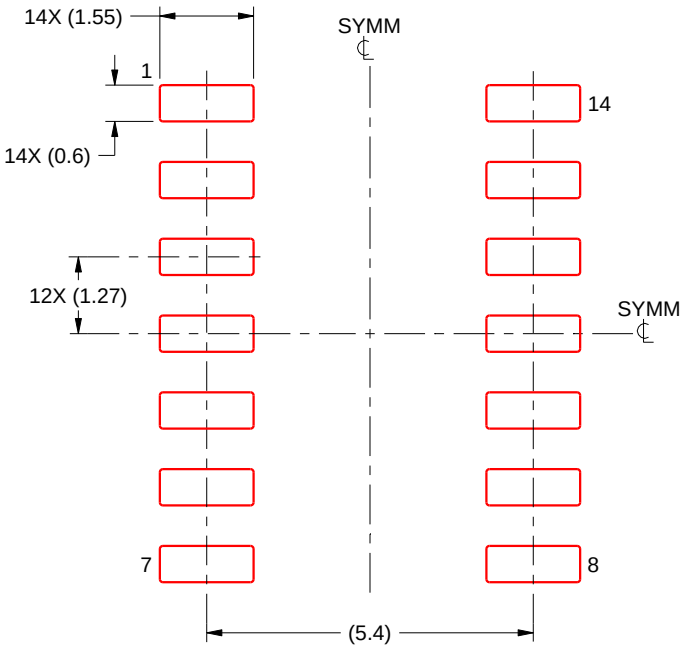
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

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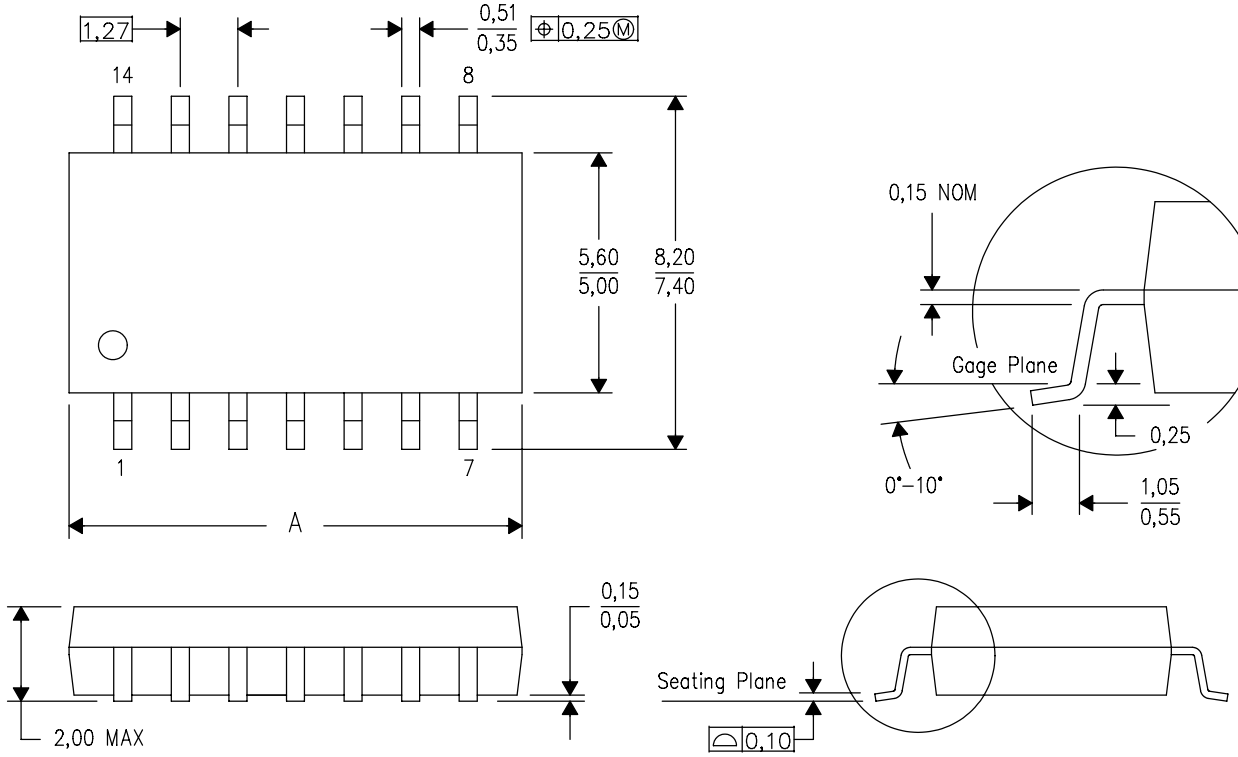
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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